SOT223 Package Type

1、 封装尺寸：

通常为 6.5mm×3.5mm，引脚间距为 2.3mm，适合表面贴装。

1. Package Dimensions

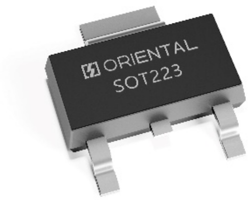
It typically measures 6.5mm × 3.5mm with a pin pitch of 2.3mm, making it suitable for surface mounting.

2、 引脚数量：

一般有 4 个引脚，其中引脚 4 为散热引脚。

2、Pin Count

It generally has 4 pins, among which Pin 4 serves as the heat dissipation pin.



3、散热能力：

通过散热引脚连接到芯片的散热焊盘，可焊接在 PCB 的大面积铜箔上，以增强散热性能，适用于输出电流

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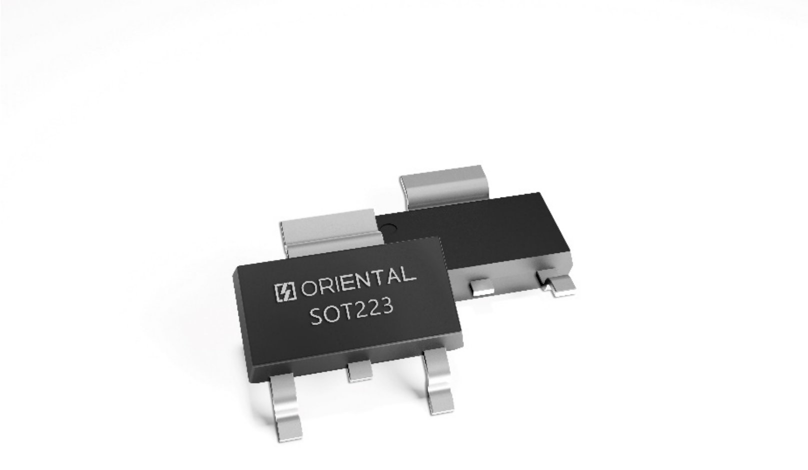
可达 1A 左右的线性稳压器和功率晶体管。

3. Heat Dissipation Capability

The heat dissipation pin is connected to the chip’ s thermal pad, which can be soldered onto a large-area copper foil on the PCB to enhance heat dissipation performance. This design is suitable for linear regulators and power transistors with an output current of around 1A.



4、应用领域：

广泛应用于电源管理、运算放大器和射频电路等场景。

4. Application Fields

It is widely used in scenarios such as power management, operational amplifiers, and radio frequency (RF) circuits.